

WAFER BONDING USING REACTIVE FOILS FOR MASSIVELY PARALLEL MICRO-ELECTROMECHANICAL SYSTEMS PACKAGING

Tanya Jegeris Snyder

Robert H. Yi

Robert Edward Wilson

ABSTRACT

A method for forming device packages includes forming a perimeter comprising a reactive foil and a bonding material interposed between a first wafer and a second wafer, pressing the first and the second wafers against the reactive foil and the bonding material, initiating the reactive foil, wherein the reactive foil heating the bonding material to create a bond between the first and the second wafers, and singulating the first and the second wafers into the device packages.